

# semiconductor packaging news

EV Group Brings High-Speed High-Precision Metrology to 3D Heterogeneous Integration – November 19, 2021

## semiconductor packaging news

We search for industry news, so you don't need to.

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November 19, 2021

### Electronics Packaging - From Afterthought to Differentiator

Electronics packaging is generally divided into three major areas, traditional packaging -- also called standard or mainstream packaging, and sometimes even just "Others": advanced packaging and emerging packaging technologies. Traditional packaging is everything with wire or ribbon bond interconnects on a ceramic, metal lead frame, or organic laminated substrates, and it is typically a single ...

**3DInCites**



#### 2x Faster, 1/2 the Capital Cost, 1/2 the Footprint

Looking for revolutionary productivity for your advanced technologies? YES Plasma Resist/Descum Systems have high throughput & strip rate. **Yield Engineering Systems, Inc.**



#### Do you need wafer-wands with flexible hoses?

Our push button wafer wands turn off the air-flow when the wand is returned to the mating wand holder. Conserves factory air supply. **Virtual Industries, Inc.**



### A Broad Look Inside Advanced Packaging

Choon Lee, chief technology officer of JCET, sat down with Semiconductor Engineering to talk about the semiconductor market, Moore's Law, chiplets, fan-out packaging ... **Semiconductor Engineering**

### Power Modules: Typical Failure Modes and how to Avoid them

The soldered interface between the power die and the substrate to the base plate are critical points for failure. Learn how to reduce these failures.

**Technical Paper**

### S. Korea, ASML vow to boost cooperation in semiconductor sector

South Korea and ASML Holding N.V., the world's leading photolithography equipment maker, agreed to enhance cooperation for resilient supply chains of semiconductors and ...

**Yonhap News Agency**

### Technical Papers

- [Preparing TEM Specimens and Atom Probe Tips by Laser Machining](#)
- [High Thermal Non-Conductive Die Attach](#)
- [High-Resolution Roughness Metrology for the Wafer Fab](#)
- [Efficient Manufacture of IR Sensors](#)
- [Qualifying the ExposedPad TQFP for AEC-Q006 Grade 0](#)
- [How to Wire Pull?](#)
- [Monolithic Magnetic Sensors Manufactured by Selective Laser Annealing](#)

### Merry Christmas and Happy New Year

To our friends and readers around the world, may you find peace and happiness during the holiday season. We wish you and your families a happy holiday. We'll be back after New Year's.

**Circuitnet Media LLC**



Today's Sponsor

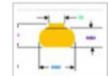


### Test Your Knowledge

Which of the following was built first: Great Wall of China, Stonehenge, The Parthenon  
*See answer below.*

### Gold Planar Bumps for Flip Chip Bonding with Challenging Applications

Achieving consistent, quality Au Planar bumps has been a challenge. This case study explore these difficult specifications and how to achieve them. **Palomar Technologies Inc.**



### Press Releases

#### EV Group Brings High-Speed High-Precision Metrology to 3D Heterogeneous Integration

EV Group unveiled the EVG540 NT2 automated metrology system, which provides overlay and critical dimension (CD) measurements for wafer-to-wafer (W2W), die-to-wafer ...

**EV Group**

#### ITW EAE to Showcase New Printer and Dispenser Developments at Semicon Taiwan

ITW EAE will be showcasing its latest printer and dispenser developments at Semicon Taiwan, December 28-30 at the Nangang Exhibition Center in Taipei. Applications Experts ...

**ITW EAE**

#### Park Systems Announces Combined AFM and WLI Tool

Park Systems presents Park NX-Hybrid WLI, the first fully integrated system that combines Atomic Force Microscopy (AFM) with White Light Interferometer (WLI) profilometry. White light ...

### Dyanloy® Conductive Solutions for Electronics Packaging

Dyanloy® Conductive Solutions offers room-temperature and user-friendly silver-filled adhesives, coatings, and lubricants.

**EMD Electronics**



### Plasma Clean, Etch and RIE in One Machine

The PE-100 convertible allows you to perform plasma cleaning, isotropic etching and reactive ion etching (RIE) in the same system!

**Plasma Etch**



### Ford partners with GlobalFoundries to increase chip supplies

Ford Motor plans to increase its short- and long-term supply of semiconductor chips through a new partnership with GlobalFoundries. The Detroit automaker and ...

**CNBC**

### Apple to begin letting people fix their own iPhones

Apple Inc said it would begin allowing people to fix gadgets they buy from the Silicon Valley giant in a concession seen as a victory for "right-to-repair" advocates. The iPhone ...

**Taipei Times**

### US-China tech war clouds Hynix's plans for a key fab

Plans by South Korea's SK Hynix Inc to overhaul a huge facility in China so it can make memory chips more efficiently are in jeopardy, because US officials do not want ...

**Taipei Times**

**EVG**  
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Activates surfaces for adhesion  
Prepares surfaces for Direct Bonding  
QNTOX Atmospheric Plasma

### End In Sight For Chip Shortages?

The current wave of semiconductor and IC packaging shortages is expected to extend well into 2022, but there are also signs that supply may finally catch up with demand. ...

**Semiconductor Engineering**

### Texas Instruments to build a \$30 billion semiconductor chip manufacturing campus

Dallas-based Texas Instruments has announced plans to build as many as four new semiconductor chip manufacturing plants in Sherman, potentially investing ...

**Tech Xplore**

### Semiconductor Photomask Revenues Predicted To Increase In 2021

A majority (72%) of industry luminaries surveyed in July predict an increase in photomask revenues for 2021. SEMI also predicts revenues to increase around 9% from ...

**Semiconductor Engineering**

### NanoResolution MRS™ Sensor

3D High precision optical sensor for packaging inspection & metrology. Inspect shiny or mirror-like surfaces with sub-micrometer accuracy for features as small as 25µm.

**CyberOptics Corporation**



### Your Chips are Precious Cargo

Gel-Pak's LCS2™ Waffle Pack Lid eliminates component out-of-pocket defects resulting from die migration so your valuable devices arrive defect-free & ready for assembly.

**Gel-Pak, a Division of Delphon**



### Park Systems

#### Amkor's Double Sided Molded BGA Solutions

To improve the integration of RFFE solutions, Amkor offers a DSMBGA package that allows molded assembly of components on both sides of the substrate.

**Amkor Technology, Inc.**



#### Quote of the Day

"If all pulled in one direction, the world would keel over."

**Yiddish proverb**

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**Amkor Technology, Inc.**



#### Etching and Stripping for WLP

High volume manufacturing solution for wafer bumping and advanced packaging. Dry plasma processing for etching materials including Dry films, PR, PI & PBO as well as Oxide, Nitride & dielectrics.

**Trymax Semiconductor Equipment**



#### What Year Was It?

##### Lincoln Delivers Gettysburg Address

At the dedication of a military cemetery during the Civil War, President Lincoln delivers one of the most memorable speeches in American history.



**The day was Nov 19. What year was it?**

#### High Volume Configuration MRSI-705 Die Bonder

Improved configuration with optional turret tool changer, for shorter cycle time in eutectic and epoxy die bonding. Learn more.

**MRSI Systems**



#### Big Ideas, The Best Team, The Right Solutions.

Learn about industry-leading photolithography solutions and advanced semiconductor inspection systems. Visit us virtually at SEMICON West 2021!

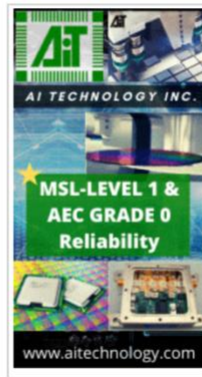
**Nikon Precision Inc.**



### Samsung cements top spot in DRAM market in Q3

Samsung Electronics Co. boosted its market presence in the global memory market in the third quarter, further consolidating its dominant position in the segment ...

Yonhap News Agency



### Cartoon of the Day



"We used to have a casual dress code but too many people mistook our office for a homeless shelter."

Copyright © Randy Glasbergen

### Calendar

- [Nov 19, 2021: SEMICON Europa 2021 | In-person Event](#)
- [Dec 6, 2021: Overview of Semiconductor Manufacturing \( During SEMI West week\)](#)
- [Dec 7, 2021: SEMICON West 2021 | Hybrid Event](#)
- [Dec 11, 2021: IEEE International Electron Devices Meeting](#)

#### NanoResolution MRS™ Sensor

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Gel-Pak's LCS2™ Waffle Pack Lid eliminates component out-of-pocket defects resulting from die migration so your valuable devices arrive defect-free & ready for assembly.

**Gel-Pak, a Division of Delphon**



#### SiP Printing of the Future

Welco®AP5112 Type 7 paste enables the single-step printing process for both flip-chip & passive component attach, which significantly reduces assembly cost and solder defects.

**Heraeus Advanced Packaging**



#### Test Your Knowledge Answer

Which of the following was built first: Great Wall of China, Stonehenge, The Parthenon  
Answer: Stonehenge (~3000 BC). Great Wall of China (771-476 BC), Stonehenge, The Parthenon (432 BC)

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